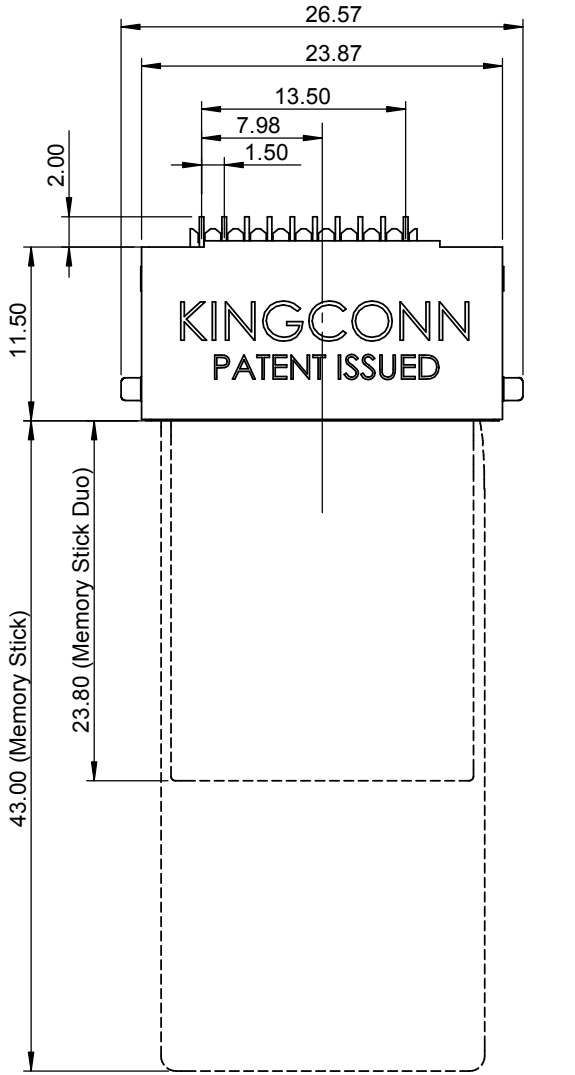
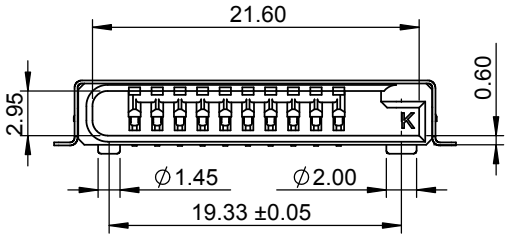
更改 REV	設 變 內 容 MODIFICATION
E	ECR00780
F	ECN00868
G	ECN01167

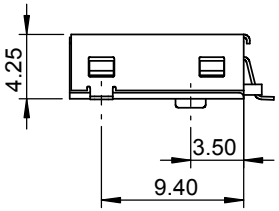


NOTES :
1. MATERIAL :
   INSULATOR : LCP UL 94V-0,IVORY
   CONTACT : COPPER ALLOY
2. PART NO : MSMS- X 9- X111

PACKING:
0:TRAY
1:CARRIER

PANTING
F CONTACT:GOLD FLASH OVER 50u"MIN.NICKEL
SOLDER TAIL:100u"MIN.Sn OVER 50u"NICKEL
B CONTACT:10u"MIN.Au OVER 50u"MIN.NICKEL
SOLDER TAIL:100u"MIN.Sn OVER NICKEL

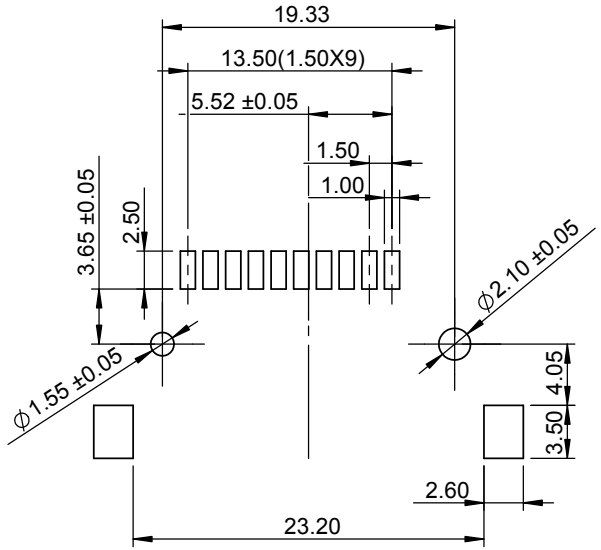




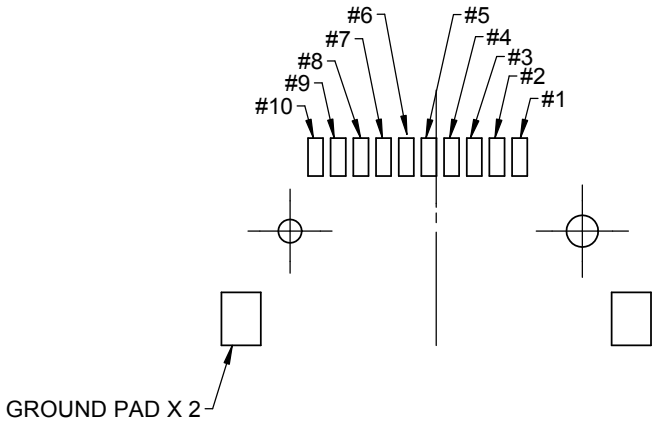
GENERIAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X.± 0.50	X.°± 5°		
.X± 0.30	.X°± 2°	名 稱(TITLE) MemoryStick & MemoryStick Duo Connector Reverse type	
.XX± 0.20	.XX°± 1°		
單 位(UNIT) mm	料 號(PART NO.) MSMS-X9-X111	圖 號(DWG NO.) MSMS-X9-X111-G	
審 核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)	比 例 SCALE 2:1 / 張 數 SHEET 1/2 / 角 法 PROJ. / 更 改 REV G

QP-701-03

更改 REV	設 變 內 容 MODIFICATION
E	ECR00780
F	ECN00868
G	ECN01167



RECOMMEND PCB LAYOUT



PIN DEFINITION

MS#1	VSS
MS#2	BS
MS#3	DATA1
MS#4	SDIO/DATA0
MS#5	DATA2
MS#6	INS
MS#7	DATA3
MS#8	SCLK
MS#9	VCC
MS#10	VSS

GENERIAL TOLERANCE	
X.± 0.50	X.°± 5°
.X± 0.30	.X°± 2°
.XX± 0.20	.XX°± 1°
	.XXX°± 0.5°

KINGCONN 皇海科技股份有限公司

名 稱(TITLE) MemoryStick & MemoryStick Duo Connector Reverse type

單 位(UNIT)	料 號(PART NO.)	圖 號(DWG NO.)
mm	MSMS-X9-X111	MSMS-X9-X111-G

審 核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)	比 例 SCALE 2:1	張 數 SHEET 2/2
			角 法 PROJ.	更 改 REV G